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- Meet or Exceed the Requirements of TIA/EIA-422-B, TIA/EIA-485-A[†] and ITU Recommendations V.11 and X.27
- Operate at Data Rates up to 35 Mbaud
- Four Skew Limits Available: SN65ALS176...15 ns SN75ALS176...10 ns SN75ALS176A...7.5 ns SN75ALS176B...5 ns
- Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments
- Low Supply-Current Requirements ... 30 mA Max
- Wide Positive and Negative Input/Output Bus-Voltage Ranges
- Thermal Shutdown Protection
- Driver Positive and Negative Current Limiting
- Receiver Input Hysteresis
- Glitch-Free Power-Up and Power-Down
 Protection
- Receiver Open-Circuit Fail-Safe Design

description

The SN65ALS176 and SN75ALS176 series differential bus transceivers are designed for bidirectional data communication on multipoint bus transmission lines. They are designed for balanced transmission lines and meet TIA/EIA-422-B, TIA/EIA-485-A, and ITU Recommendations V.11 and X.27.

The SN65ALS176 and SN75ALS176 series combine a 3-state, differential line driver and a differential input line receiver, both of which operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, that can be connected together externally to function as a direction control. The driver differential outputs and the receiver differential inputs are connected internally to form a differential input/output (I/O) bus port that is designed to offer minimum loading to the bus when the driver is disabled or $V_{CC} = 0$. This port features wide positive and negative common-mode voltage ranges, making the device suitable for party-line applications.

The SN65ALS176 is characterized for operation from -40° C to 85° C. The SN75ALS176 series is characterized for operation from 0° C to 70° C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

[†] These devices meet or exceed the requirements of TIA/EIA-485-A, except for the Generator Contention Test (para. 3.4.2) and the Generator Current Limit (para. 3.4.3). The applied test voltage ranges are –6 V to 8 V for the SN75ALS176, SN75ALS176A, and SN75ALS176B and -4 V to 8 V for the SN65ALS180.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



D OR P PACKAGE (TOP VIEW) R[1 8] V_{CC} RE[2 7] B DE[3 6] A D[4 5] GND

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AVAILABLE OPTIONS										
		PACKAGED	DEVICES							
TA	^t sk(lim) [†]	SMALL OUTLINE (D) [‡]	PLASTIC DIP (P)							
0°C to 70°C	10 7.5 5	SN75ALS176D SN75ALS176AD SN75ALS176BD	SN75ALS176P SN75ALS176AP SN75ALS176BP							
–40°C to 85°C	15	SN65ALS176D	SN65ALS176P							

[†] This is the maximum range that the driver or receiver delay times vary over temperature, V_{CC}, and process (device to device).

[‡] The D package is available taped and reeled. Add the suffix R to the device type (e.g., SN75ALS176DR).

Function Tables

DRIVER

INPUT	ENABLE	OUT	PUTS
D	DE	Α	В
Н	Н	Н	L
L	н	L	Н
Х	L	Z	Z

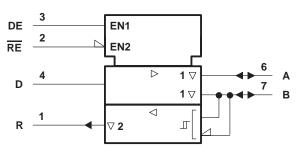
H = high level, L = low level, X = irrelevant, Z = high impedance

RECEIVER

DIFFERENTIAL INPUTS A–B	ENABLE RE	OUTPUT R
$V_{ID} \ge 0.2 V$	L	Н
$-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$	L	?
$V_{ID} \le -0.2 V$	L	L
Х	н	Z
Inputs open	L	Н

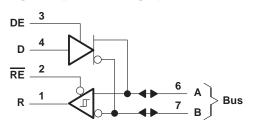
H = high level, L = low level, X = irrelevant, Z = high impedance

logic symbol§



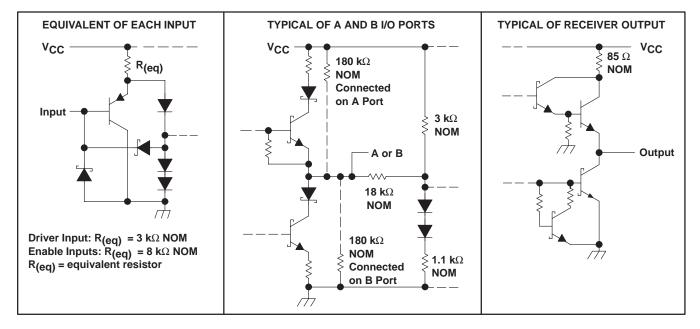
§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





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schematics of inputs and outputs

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} (see Note 1)	
Voltage range at any bus terminal	–7 V to 12 V
Enable input voltage, V _I	5.5 V
Package thermal impedance, θ_{JA} (see Note 2): D package	97°C/W
P package	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stg}	–65°C to 150°C

⁺ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.

2. The package thermal impedance is calculated in accordance with JESD 51.



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recommended operating conditions (unless otherwise noted)

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.75	5	5.25	V
Input voltage at any bus terminal (separately or common mode), VI or VIC				12	V
input voltage at any bus terminal (separately of common mode), v of v[C				-7	v
High-level input voltage, VIH	D, DE, and RE	2			V
Low-level input voltage, VIL	D, DE, and RE			0.8	V
Differential input voltage, VID (see Note 3)				±12	V
High-level output current, IOH	Driver			-60	mA
ngn-level output current, IOH	Receiver			-400	μΑ
	Driver			60	mA
Low-level output current, IOL Receiver				8	ША
Operating free-air temperature, T_{Δ}	SN65ALS176	-40		85	°C
Operating nee-an temperature, 1A	SN75ALS176 series	0		70	C

NOTE 3: Differential input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.



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DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CC	ONDITIONS [†]	MIN	TYP‡	MAX	UNIT
VIK	Input clamp voltage	Ij = -18 mA				-1.5	V
VO	Output voltage	I _O = 0		0		6	V
VOD1	Differential output voltage	I _O = 0		1.5		6	V
	Differential output voltage	R _L = 100 Ω,	See Figure 1	1/2V _{OD1} or 2§			V
		R _L = 54 Ω,	See Figure 1	1.5	2.5	5	V
V _{OD3}	Differential output voltage	$V_{test} = -7 V \text{ to } 12 V,$	See Figure 2	1.5		5	V
$\Delta V_{OD} $	Change in magnitude of differential output voltage¶	$R_L = 54 \Omega$ or 100 Ω,	See Figure 1			±0.2	V
Voc	Common-mode output voltage	R _L = 54 Ω or 100 Ω,	See Figure 1			3 –1	V
$\Delta V_{OC} $	Change in magnitude of common-mode output voltage¶	$R_L = 54 \Omega$ or 100 Ω,	See Figure 1			±0.2	V
	Output current	Outputs disabled	V _O = 12 V			1	mA
10	Oupurcurrent	(see Note 4)	$V_{O} = -7 V$			-0.8	IIIA
IIН	High-level input current	VI = 2.4 V				20	μΑ
۱ _{IL}	Low-level input current	V _I = 0.4 V				-400	μΑ
		$V_{O} = -4 V$	SN65ALS176			-250	
		VO = -6 V	SN75ALS176			-250	
los	Short-circuit output current#	$V_{O} = 0$				-150	mA
		$V_{O} = V_{CC}$				250	
		V _O = 8 V				250	
ICC	Supply current	No load	Outputs enabled		23	30	mA
			Outputs disabled		19	26	

[†] The power-off measurement in TIA/EIA-422-B applies to disabled outputs only and is not applied to combined inputs and outputs.

[‡] All typical values are at V_{CC} = 5 V and T_A = 25°C.

§ The minimum V_{OD2} with a 100- Ω load is either 1/2 V_{OD1} or 2 V, whichever is greater.

 $\int \Delta |V_{OD}|$ and $\Delta |V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC} , respectively, that occur when the input is changed from one logic state to the other.

[#] Duration of the short circuit should not exceed one second for this test.

NOTE 4: This applies for power on and power off. Refer to TIA/EIA-485-A for exact conditions. The TIA/EIA-422-B limit does not apply for a combined driver and receiver terminal.



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switching characteristics over recommended ranges of supply voltage and operating free-air temperature range (unless otherwise noted)

SN65ALS176

PARAMETER		PARAMETER TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
td(OD)	Differential output delay time	R _L = 54 Ω,	$C_{L} = 50 \text{ pF},$	See Figure 3			15	ns
^t sk(p)	Pulse skew [‡]	$R_L = 54 \Omega$,	C _L = 50 pF,	See Figure 3		0	2	ns
^t sk(lim)	Pulse skew§	$R_L = 54 \Omega$,	C _L = 50 pF,	See Figure 3			15	ns
^t t(OD)	Differential output transition time	RL = 54 Ω,	С _L = 50 рF,	See Figure 3		8		ns
^t PZH	Output enable time to high level	RL = 110 Ω,	С _L = 50 рF,	See Figure 4			80	ns
t _{PZL}	Output enable time to low level	R _L = 110 Ω,	С _L = 50 рF,	See Figure 5			30	ns
^t PHZ	Output disable time from high level	R _L = 110 Ω,	С _L = 50 рF,	See Figure 4			50	ns
^t PLZ	Output disable time from low level	R _L = 110 Ω,	C _L = 50 pF,	See Figure 5			30	ns

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[‡]Pulse skew is defined as the $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

§ Skew limit is the maximum difference in propagation delay times between any two channels of any two devices.

SN75ALS176, SN75ALS176A, SN75ALS176B

	PARAMETER			TEST CONDITIO	NS	MIN	TYP†	MAX	UNIT
	D''' '' ' ' ' '	'ALS176				3	8	13	
	Differential output delay time	'ALS176A	R _L = 54 Ω,	$C_{L} = 50 \text{ pF},$	See Figure 3	4	7	11.5	ns
		'ALS176B				5	8	10	
t _{sk(p)}	Pulse skew [‡]		RL = 54 Ω,	$C_{L} = 50 \text{ pF},$	See Figure 3		0	2	ns
		'ALS176						10	
^t sk(lim)	Pulse skew§	'ALS176A	R _L = 54 Ω,	$C_{L} = 50 \text{ pF},$	See Figure 3			7.5	ns
		'ALS176B						5	
tt(OD)	Differential output transit	tion time	$R_L = 54 \Omega$,	C _L = 50 pF,	See Figure 3		8		ns
^t PZH	Output enable time to hi	gh level	R _L = 110 Ω,	C _L = 50 pF,	See Figure 4		23	50	ns
t _{PZL}	Output enable time to lo	w level	R _L = 110 Ω,	C _L = 50 pF,	See Figure 5		14	20	ns
^t PHZ	Output disable time from	n high level	R _L = 110 Ω,	C _L = 50 pF,	See Figure 4		20	35	ns
^t PLZ	Output disable time from	n low level	R _L = 110 Ω,	C _L = 50 pF,	See Figure 5		8	17	ns

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] Pulse skew is defined as the $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

§ Skew limit is the maximum difference in propagation delay times between any two channels of any two devices.

S	SYMBOL EQUIVALENTS								
DATA-SHEET PARAMETER	TIA/EIA-422-B	TIA/EIA-485-A							
Vo	V _{oa} , V _{ob}	V _{oa} , V _{ob}							
IVOD1	Vo	Vo							
IV _{OD2} I	V_t (R _L = 100 Ω)	$V_t (R_L = 54 \Omega)$							
V _{OD3}	None	V _t (test termination measurement 2)							
	$ V_t - \overline{V}_t $	$ V_t - \overline{V}_t $							
V _{OC}	V _{os}	V _{os}							
$\Delta V_{OC} $	$ V_{OS} - \overline{V}_{OS} $	$ V_{OS} - \overline{V}_{OS} $							
los	I _{sa} , I _{sb}	None							
IO	_{xa} , _{xb}	I _{ia} , I _{ib}							



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RECEIVER SECTION

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST C	ONDITIONS	MIN	TYP†	MAX	UNIT
V_{IT+}	Positive-going input threshold voltage	V _O = 2.7 V,	I _O = -0.4 mA			0.2	V
V_{IT-}	Negative-going input threshold voltage	V _O = 0.5 V,	I _O = 8 mA	-0.2‡			V
V _{hys}	Hysteresis voltage (V _{IT+} – V _{IT} –)				60		mV
VIK	Enable-input clamp voltage	lj = -18 mA				-1.5	V
∨он	High-level output voltage	V _{ID} = 200 mV, See Figure 6	I _{OH} = -400 μA,	2.7			V
VOL	Low-level output voltage	V _{ID} = -200 mV, See Figure 6	I _{OL} = 8 mA,			0.45	V
IOZ	High-impedance-state output current	$V_{O} = 0.4 \text{ V} \text{ to } 2.4 \text{ V}$				±20	μΑ
		Other input = 0 V	Other input = 0 V VI = 12 V		1	mA	
٧I	Line input current	(see Note 5)	$V_{I} = -7 V$			-0.8	ША
Ι _Η	High-level-enable input current	V _{IH} = 2.7 V				20	μΑ
١ _١ ٢	Low-level-enable input current	V _{IL} = 0.4 V				-100	μΑ
rı	Input resistance			12	20		kΩ
IOS	Short-circuit output current	V _{ID} = 200 mV,	VO = 0	-15		-85	mA
100	Supply ourroat	Notood	Outputs enabled		23	30	~^^
ICC	Supply current	No load	Outputs disabled		19	26	mA

[†] All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

[‡] The algebraic convention, in which the less positive (more negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.

NOTE 5: This applies for power on and power off. Refer to TIA/EIA-485-A for exact conditions.



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switching characteristics over recommended ranges of supply voltage and operating free-air temperature range (unless otherwise noted)

SN65ALS176

	PARAMETER	TEST CO	NDITIONS	MIN	түр†	MAX	UNIT
^t pd	Propagation time	$V_{ID} = -1.5 V$ to 1.5 V, See Figure 7	C _L = 15 pF,			25	ns
^t sk(p)	Pulse skew§	$V_{ID} = -1.5 V$ to 1.5 V, See Figure 7	C _L = 15 pF,		0	2	ns
^t sk(lim)	Pulse skew¶	$R_L = 54 \Omega$, See Figure 3	C _L = 50 pF,			15	ns
^t PZH	Output enable time to high level	C _L = 15 pF,	See Figure 8		11	18	ns
tPZL	Output enable time to low level	C _L = 15 pF,	See Figure 8		11	18	ns
^t PHZ	Output disable time from high level	C _L = 15 pF,	See Figure 8			50	ns
^t PLZ	Output disable time from low level	C _L = 15 pF,	See Figure 8			30	ns

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

Pulse skew is defined as the |tpLH - tpHL| of each channel of the same device.

I Skew limit is the maximum difference in propagation delay times between any two channels of any two devices.

SN75ALS176, SN75ALS176A, SN75ALS176B

	PARAMETER		TEST CO	NDITIONS	MIN	түр†	MAX	UNIT
		'ALS176			9	14	19	
^t pd	Propagation time	'ALS176A	V _{ID} = −1.5 V to 1.5 V, See Figure 7	C _L = 15 pF,	10.5	14	18	ns
•		'ALS176B			11.5	11.5 13 16.5		
^t sk(p)	Pulse skew [‡]	-	$V_{ID} = -1.5 V$ to 1.5 V, See Figure 7	C _L = 15 pF,		0	2	ns
		'ALS176					10	
^t sk(lim)	Pulse skew§	'ALS176A	$R_L = 54 \Omega$, See Figure 3	CL = 50 pF,			7.5	ns
		'ALS176B					5	
^t PZH	Output enable time to	o high level	C _L = 15 pF,	See Figure 8		7	14	ns
t _{PZL}	Output enable time to	o low level	C _L = 15 pF,	See Figure 8		20	35	ns
^t PHZ	Output disable time f	rom high level	C _L = 15 pF,	See Figure 8		20	35	ns
^t PLZ	Output disable time f	rom low level	C _L = 15 pF,	See Figure 8		8	17	ns

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] Pulse skew is defined as the |tpLH - tpHL| of each channel of the same device.

§ Skew limit is the maximum difference in propagation delay times between any two channels of any two devices.

PARAMETER MEASUREMENT INFORMATION

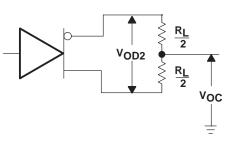


Figure 1. Driver V_{OD2} and V_{OC}



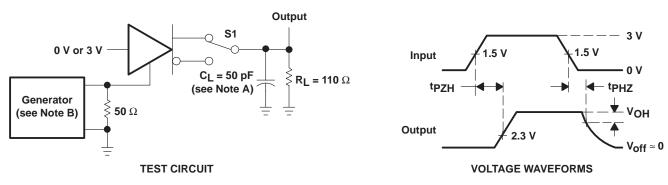
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PARAMETER MEASUREMENT INFORMATION **375** Ω **60** Ω V_{OD3} $\wedge \wedge$ Vtest **375** Ω Figure 2. Driver VOD3 3 V 1.5 V 1.5 ν Input 0 V C_L = 50 pF td(ODH) td(ODL) (see Note A) (see Note C) (see Note C) **R**_L = 54 Ω ≈2.5 V Generator Output 90% 90% Ş **50** Ω 50% (see Note B) Output 50% _10% —≈–2.5 V 10% 3 V tt(OD) **TEST CIRCUIT VOLTAGE WAVEFORMS**

NOTES: A. CL includes probe and jig capacitance.

- B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_r \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .
- C. $t_d(OD) = t_d(ODH)$ or $t_d(ODL)$

Figure 3. Driver Test Circuit and Voltage Waveforms



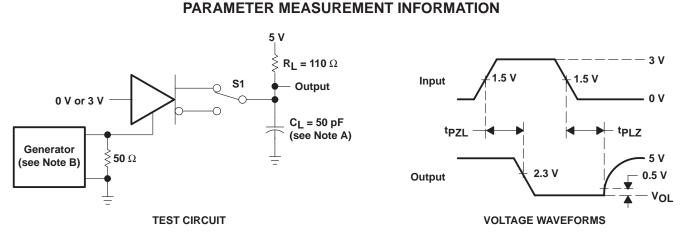
NOTES: A. Cl includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .

Figure 4. Driver Test Circuit and Voltage Waveforms



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NOTES: A. CL includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .



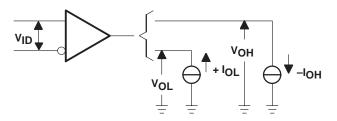
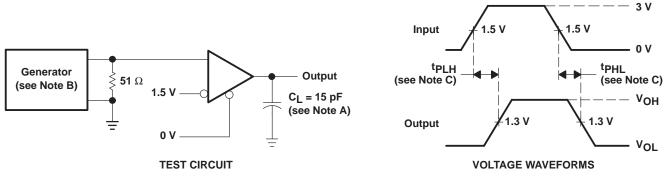


Figure 6. Receiver VOH and VOL Test Circuit



NOTES: A. C₁ includes probe and jig capacitance.

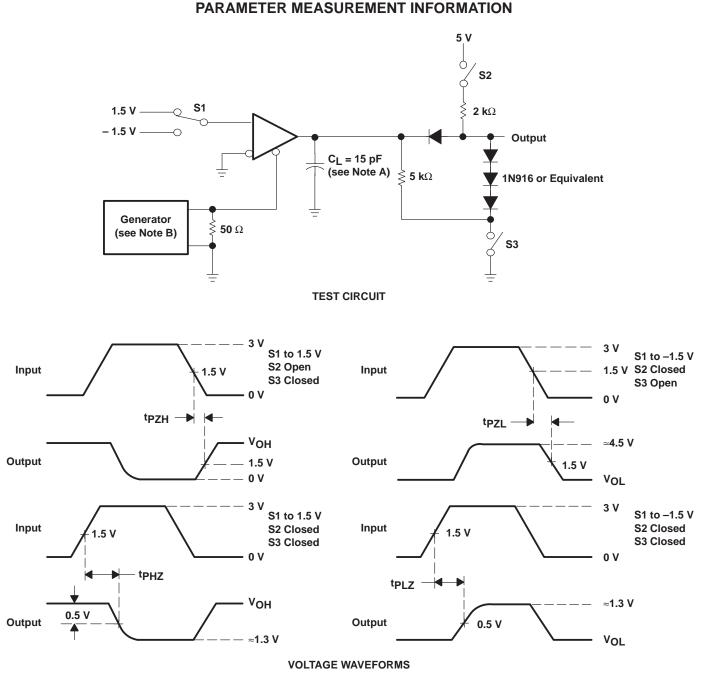
B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .

C. tpd = tPLH or tPHL

Figure 7. Receiver Test Circuit and Voltage Waveforms



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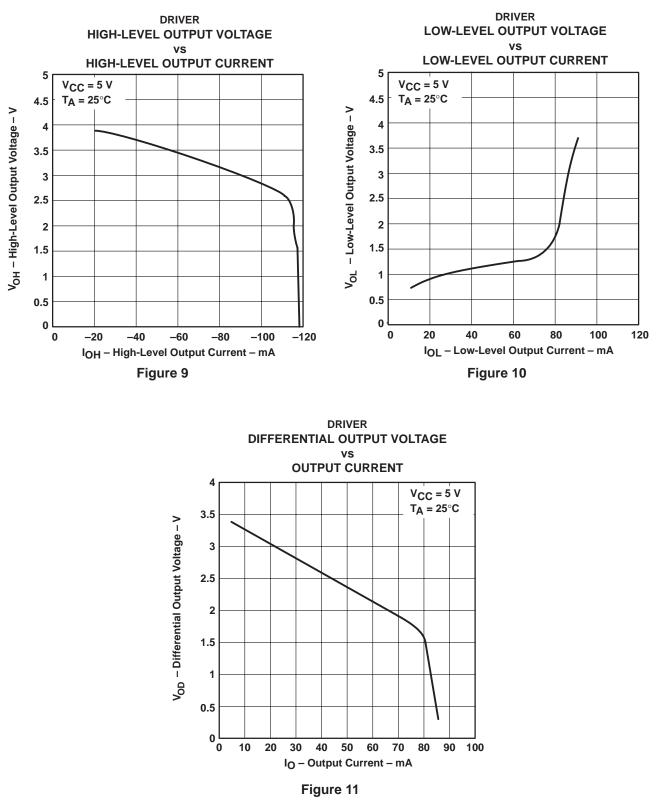
NOTES: A. CL includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 8 ns, t_f \leq 8

Figure 8. Receiver Test Circuit and Voltage Waveforms



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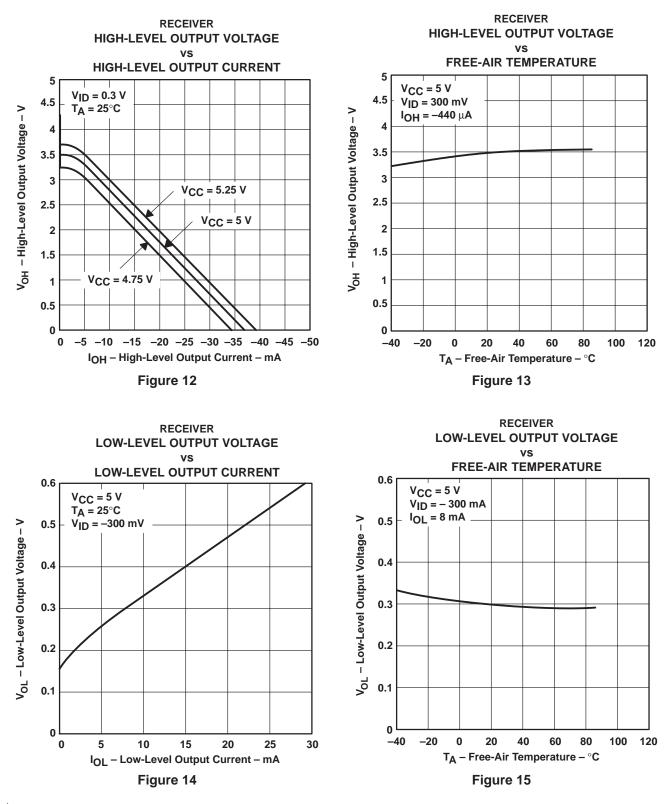
TYPICAL CHARACTERISTICS[†]

[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.



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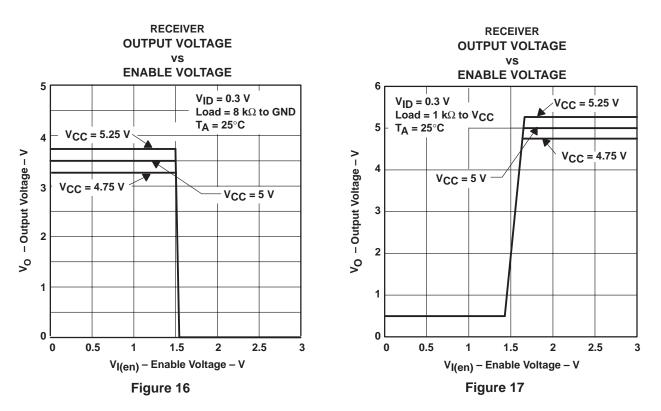




[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.



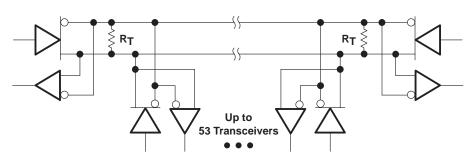
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TYPICAL CHARACTERISTICS[†]

[†]Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

APPLICATION INFORMATION



NOTE A: The line should terminate at both ends in its characteristic impedance (R_T = Z_O). Stub lengths off the main line should be kept as short as possible.

Figure 18. Typical Application Circuit



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Products		Applications	
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Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
Low Power Wireless	www.ti.com/lpw	Telephony	www.ti.com/telephony
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23-Apr-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65ALS176D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS176DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS176DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS176DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS176DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS176DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS176P	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI
SN75ALS176AD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176ADE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176ADG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176ADR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176ADRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176ADRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176AP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS176APE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS176BD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176BDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176BDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176BDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176BDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176BDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176BP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS176BPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS176D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75ALS176DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS176PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



All dimensions are nominal Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65ALS176DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75ALS176ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75ALS176BDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75ALS176DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1



PACKAGE MATERIALS INFORMATION

19-Mar-2008

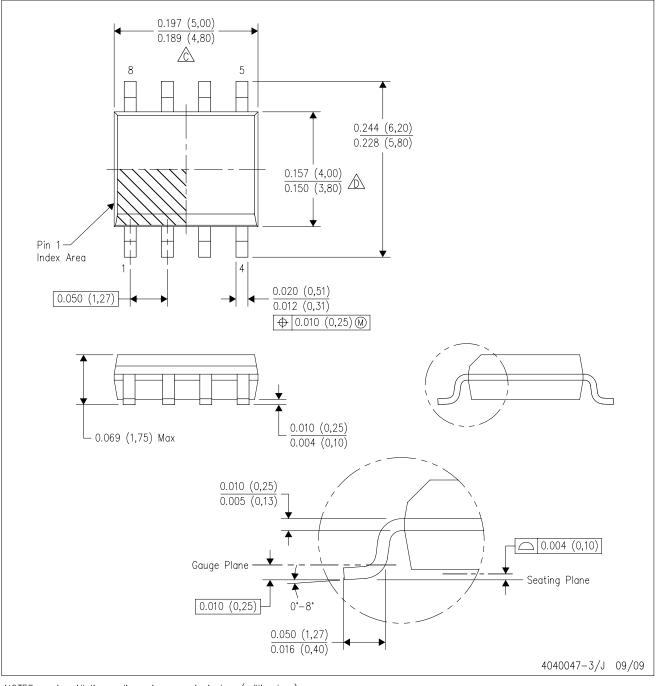


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65ALS176DR	SOIC	D	8	2500	340.5	338.1	20.6
SN75ALS176ADR	SOIC	D	8	2500	340.5	338.1	20.6
SN75ALS176BDR	SOIC	D	8	2500	340.5	338.1	20.6
SN75ALS176DR	SOIC	D	8	2500	340.5	338.1	20.6

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AA.



MECHANICAL DATA

MPDI001A - JANUARY 1995 - REVISED JUNE 1999



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN65ALS176D	ACTIVE	SOIC	D	8	75	RoHS & Green	(6) NIPDAU	Level-1-260C-UNLIM	-40 to 85	65A176	Samples
SN65ALS176DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	65A176	Samples
SN75ALS176AD	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	7A176A	Samples
SN75ALS176ADR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	7A176A	Samples
SN75ALS176ADRG4	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	7A176A	Samples
SN75ALS176AP	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	75ALS176A	Samples
SN75ALS176BD	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	7A176B	Samples
SN75ALS176BDR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	7A176B	Samples
SN75ALS176BP	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	75ALS176B	Samples
SN75ALS176D	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75A176	Samples
SN75ALS176DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75A176	Samples
SN75ALS176P	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	75ALS176	Samples
SN75ALS176PE4	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	75ALS176	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.



PACKAGE OPTION ADDENDUM

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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Texas

*All dimensions are nominal

STRUMENTS

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65ALS176DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75ALS176ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75ALS176BDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75ALS176DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1



www.ti.com

PACKAGE MATERIALS INFORMATION

9-Aug-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65ALS176DR	SOIC	D	8	2500	340.5	336.1	25.0
SN75ALS176ADR	SOIC	D	8	2500	340.5	336.1	25.0
SN75ALS176BDR	SOIC	D	8	2500	340.5	336.1	25.0
SN75ALS176DR	SOIC	D	8	2500	340.5	336.1	25.0

TEXAS INSTRUMENTS

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9-Aug-2022

TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
SN65ALS176D	D	SOIC	8	75	507	8	3940	4.32
SN75ALS176AD	D	SOIC	8	75	507	8	3940	4.32
SN75ALS176AP	Р	PDIP	8	50	506	13.97	11230	4.32
SN75ALS176BD	D	SOIC	8	75	507	8	3940	4.32
SN75ALS176BP	Р	PDIP	8	50	506	13.97	11230	4.32
SN75ALS176D	D	SOIC	8	75	507	8	3940	4.32
SN75ALS176P	Р	PDIP	8	50	506	13.97	11230	4.32
SN75ALS176PE4	Р	PDIP	8	50	506	13.97	11230	4.32

D0008A



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.

- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



D0008A

EXAMPLE BOARD LAYOUT

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



D0008A

EXAMPLE STENCIL DESIGN

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

9. Board assembly site may have different recommendations for stencil design.



P(R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



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